

50 Gbit/s VCSEL (850 nm)

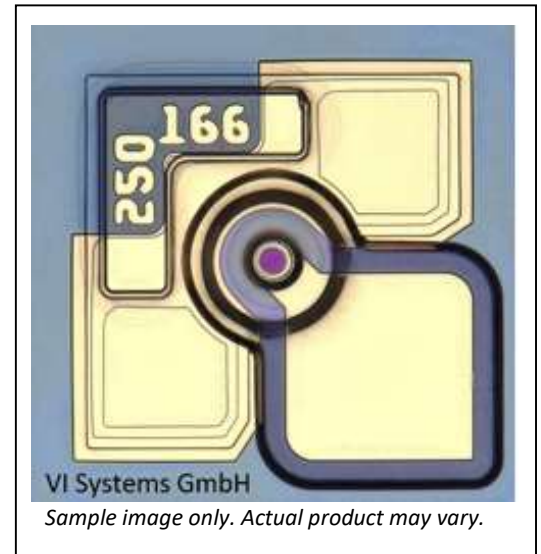
Contact type: GS/SG

Product Code:

V50-850-C1 1x1

V50-850-C4 4x1

V50-850-C12 12x1



Product Description

These compact and very high modulation rate top-emitting GaAs-based vertical cavity surface emitting laser (VCSEL) chips and 1xN (N=4,12) arrays are available as engineering samples for use in the development and evaluation of optical interconnections, optical backplanes and integrated waveguides, and next-generation optical data communications systems. The VCSELs are contacted on the top-surface individually using ground-source (GS) microprobes, wire bonds, or flip-chip bonds.

Optical aperture: ~5-7µm

Features

- 4-ch or 12 chip arrays
- Up to 56 Gbit/s per channel
- Device-to-device pitch of 250 µm
- Suitable for wire or flip-chip bonding

Applications

- Ethernet
- Proprietary optical interconnects
- Active Optical Cables (AOC)
- Short-reach 25G and 100G Ethernet

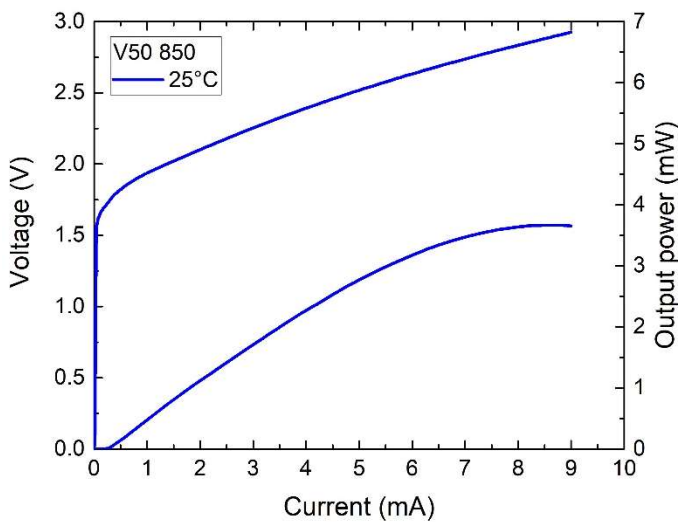
Parameter	Typical	Notes
Emission wavelength	850 nm	
Data rate	~56 Gbit/s	PAM-4
Threshold current	~ 0.5 mA	
Peak output power	~3 mW @85°C	

Electro-Optical Specifications (T = 0 to 85°C)

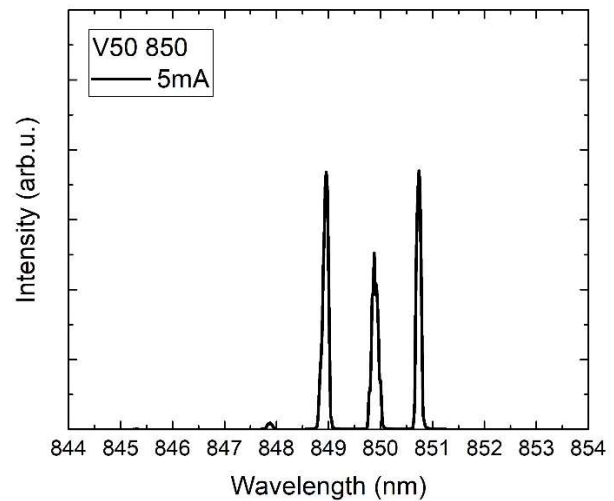
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Emission wavelength	λ		840		860	nm
Maximum data rate	BR			25	28	GBaud/s
Optical bandwidth	BW (f3dB0)			16	18	GHz
Slope efficiency	η	5 mA	0.3		0.5	W/A
Threshold current	I _{th}	25-85°C			0.8	mA
Differential resistance	R _d	5 mA		80	100	Ω
Beam divergence	Θ	FWHM		20		°
Peak output power	P _{max}			3	5	mW
Spectral bandwidth (RMS)	$\Delta\lambda_{RMS}$	5 mA		0.6	0.8	nm

*anti-reflection coating is optimized for <1% reflectivity within the range 840 nm - 960 nm

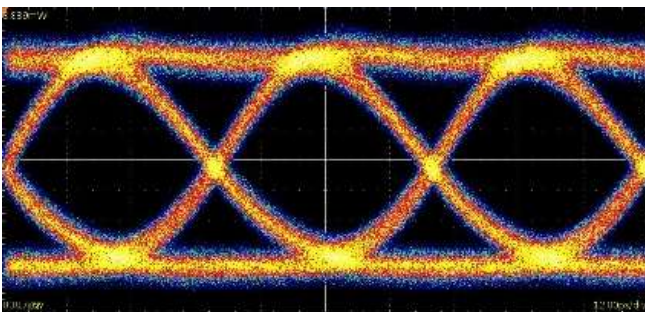
LIV Characteristics



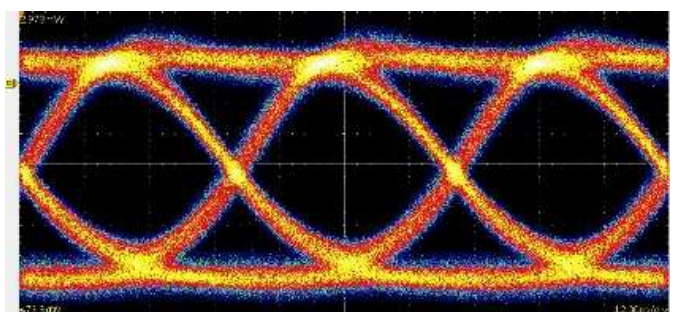
Optical Spectrum



25 Gbit/s NRZ 25°C 6 mA 500 mVpp



25 Gbit/s NRZ 85°C 6 mA 500 mVpp



Transmitter: SHF BPG 12104A. Receiver: Tektronix DSA8300 w. 80C15 Optical Sampling Module.

Eye diagrams show intrinsic performance of the chip. No equalization or signal processing was applied.

Absolute Maximum Ratings

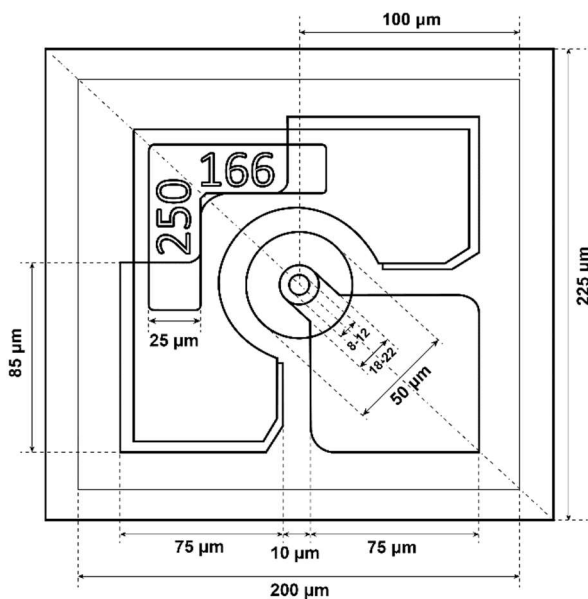
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Peak forward current	I_f				9	mA
Maximum reverse voltage	V_{rv}				5	V
Operating temperature	T_{op}				85	°C
Storage temperature	T_{st}		-40		100	°C
Soldering temperature	T_{sl}	max 260 sec			150	°C

Stress in excess of any of the individual Absolute Maximum Ratings can cause immediate irreversible damage to the component even if all other parameters are within the electro-optical specifications. Exposure to any of the Absolute Maximum Ratings for extended periods can adversely affect the reliability of these chips.

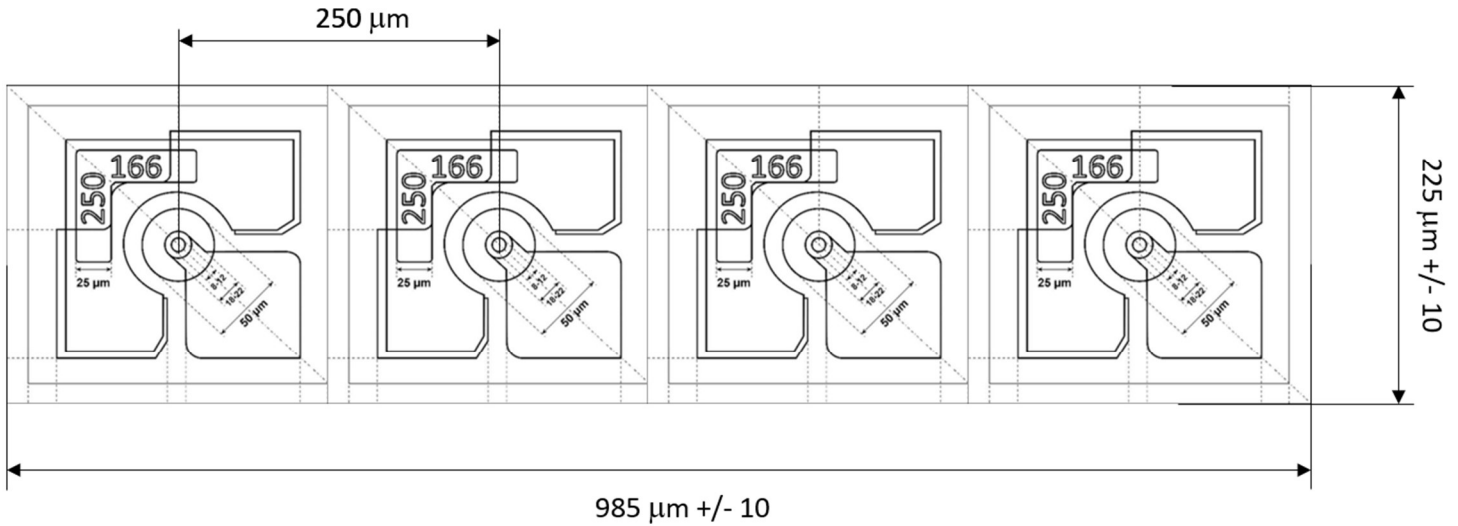
Mechanical Dimensions

Parameter	Type	Min	Typ	Max	Unit
VCSEL pitch	All		250		μm
Length 1x1 VCSEL chip	V50-850-C1		210	250	μm
Length 1x4 VCSEL array	V50-850-C4		960	1000	μm
Length 1x12 VCSEL array	V50-850-C12		2960	3000	μm
Height	All	140	150	160	μm
Width	All		210	250	μm

V50-850-C1 Dimensions

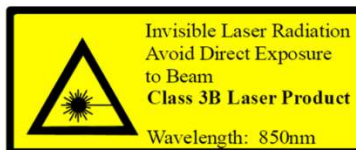


V50-850-C4 Array dimensions



Qualification Notification

The V50-850-Cxx has been qualified to meet the specifications outlined in this data. A reliability assessment report is available as a separate document.



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